

FEATURES

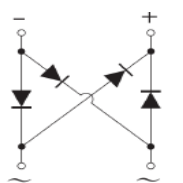
- * Ideal for printed circuit board
- * Reliable low cost construction utilizing molded plastic technique
- * High surge current capability
- * Polarity: Symbol molded on body
- * Mounting position: Any

VOLTAGE RANGE

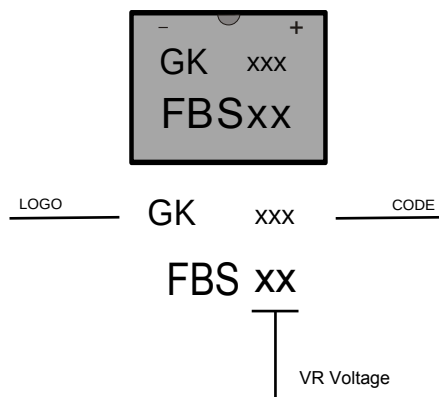
50 to 1000 Volts

CURRENT

1.0 Ampere



Internal Schematic



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

TYPE NUMBER	FBS005	FBS01	FBS02	FBS04	FBS06	FBS08	FBS10	UNITS
Maximum Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current	1.0							A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	30							A
Maximum Forward Voltage Drop per Bridge Element at 1.0A D.C.	1.3							V
Maximum DC Reverse Current Ta=25°C	5.0							μA
at Rated DC Blocking Voltage Ta=100°C	200							μA
Maximum Reverse Recovery Time (Note 1)	150				350	500		nS
Typical Junction Capacitance (Note 2)	15							pF
Typical Thermal Resistance R JA (Note 3)	75							°C/W
Operating and Storage Temperature Range Tj, Tstg	-65 — +150							°C

- NOTES: 1. Reverse Recovery Time test condition: IF=0.5A, IR=1.0A, IRR=0.25A
2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
3. Thermal Resistance from Junction to Ambient.

RATING AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD
CHARACTERISTICS

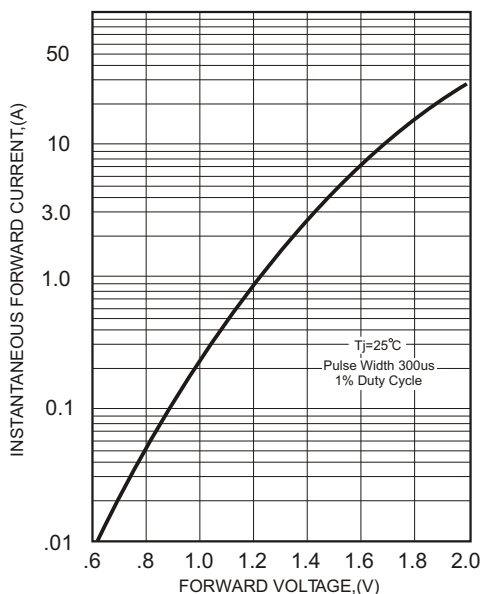


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

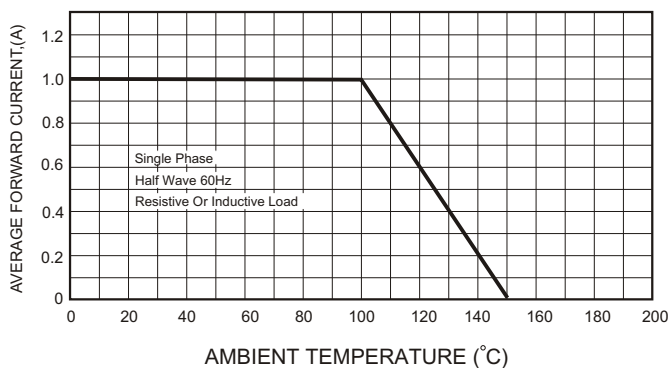


FIG.4-MAXIMUM NON-REPETITIVE FORWARD
SURGE CURRENT

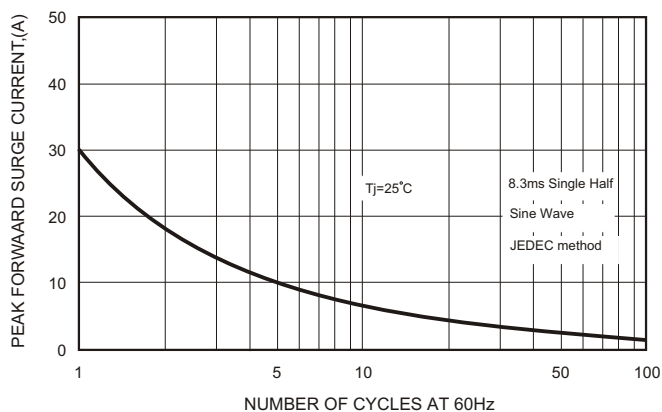
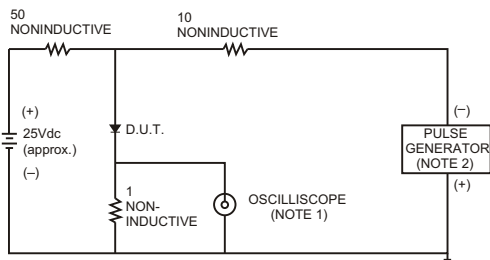


FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE
RECOVERY TIME CHARACTERISTICS



NOTES: 1. Rise Time= 7ns max., Input Impedance= 1 megohm, 22pF.

2. Rise Time= 10ns max., Source Impedance= 50 ohms.

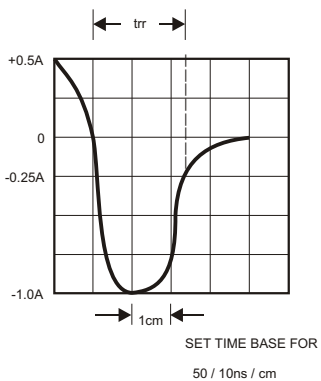
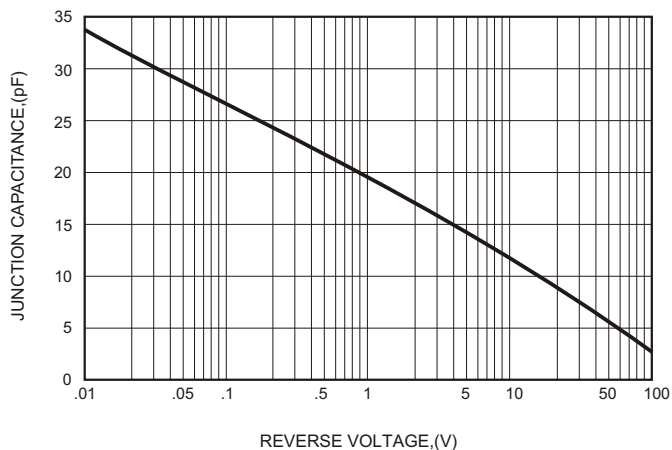
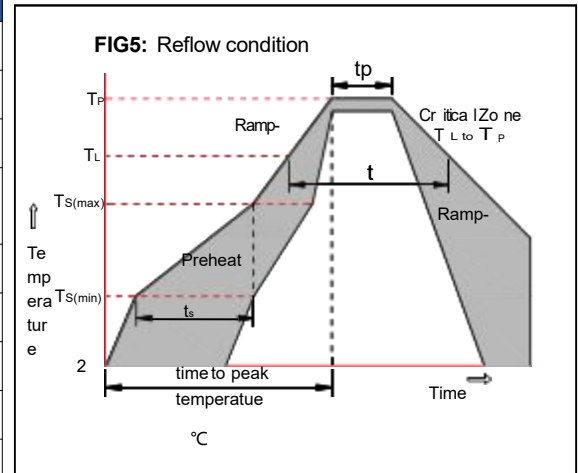


FIG.5-TYPICAL JUNCTION CAPACITANCE



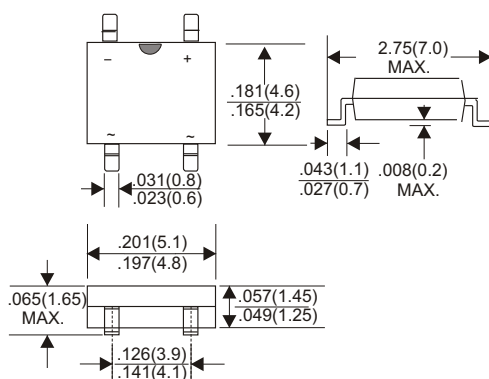
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150 °C
	-Temperature Max($T_{s(max)}$)	+200 °C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3 °C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3 °C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217 °C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5) °C
Time within 5 °C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6 °C/sec. Max
Time 25 °C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260 °C

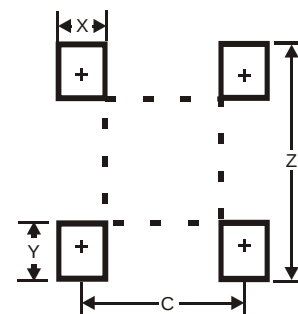


Package Dimensions & Suggested Pad Layout

ABS

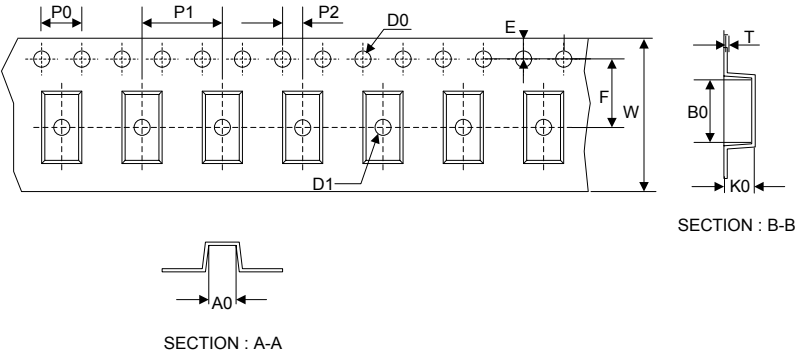
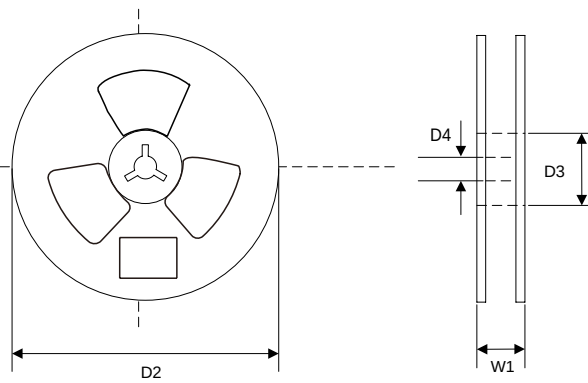


Dimensions in inches and (millimeters)



Dimensions	
Z	8.4
X	1.0
Y	2.2
C	4.0

Tape & reel specification

Tape		Symbol	Dimension (mm)
 SECTION : A-A SECTION : B-B		P0	4.00±0.20
		P1	8.00±0.20
		P2	2.00±0.20
		D0	1.60±0.15
		D1	1.60±0.15
		E	1.75±0.20
		F	5.50±0.15
		W	12.00±0.20
		A0	5.30±0.20
		B0	6.80±0.20
		K0	1.65±0.15
		T	0.23±0.10
13" Reel			
		D2	330.0±5.0
		D3	73Min.
		D4	16.0±2.5
		W1	18.0±3.0
		Quantity: 5000PCS	